# **ASSP**

# Dual Serial Input PLL Frequency Synthesizer

# **MB15F78UL**

#### **■ DESCRIPTION**

The Fujitsu MB15F78UL is a serial input Phase Locked Loop (PLL) frequency synthesizer with a 2600 MHz and a 1200 MHz prescalers. A 32/33 or a 64/65 for the 2600 MHz prescaler, and a 16/17 or a 32/33 for the 1200 MHz prescaler can be selected for the prescaler that enables pulse swallow operation.

The BiCMOS process is used, as a result a supply current is typically 4.5 mA at 2.7 V. The supply voltage range is from 2.4 V to 3.6 V. A refined charge pump supplies well-balanced output current with 1.5 mA and 6 mA selectable by serial date. The data format is the same as the previous one MB15F08SL, MB15F78SP. Fast locking is achieved for adopting the new circuit.

The new package (BCC20) decreases a mount area of MB15F78UL more than 30% comparing with the former BCC16 (for dual PLL) .

MB15F78UL is ideally suited for wireless mobile communications, such as GSM and PCS.

#### **■ FEATURES**

• High frequency operation : RX synthesizer : 2600 MHz Max.

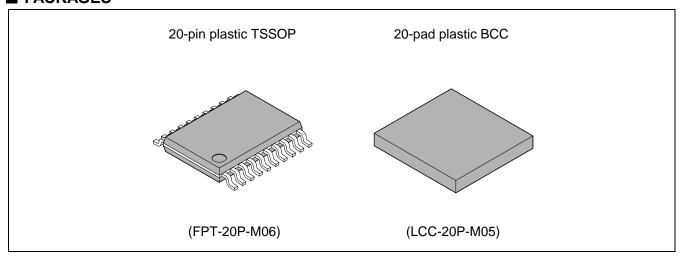
: TX synthesizer : 1200 MHz Max.

Low power supply voltage : Vcc = 2.4 to 3.6 V
 Ultra low power supply current : Icc = 4.5 mA Typ.

 $(V_{CC} = V_p = 2.7 \text{ V}, \text{ Ta} = +25 \text{ }^{\circ}\text{C}, \text{ SW}_{TX} = \text{SW}_{RX} = 0, \text{ in TX/RX locking state})$ 

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#### ■ PACKAGES



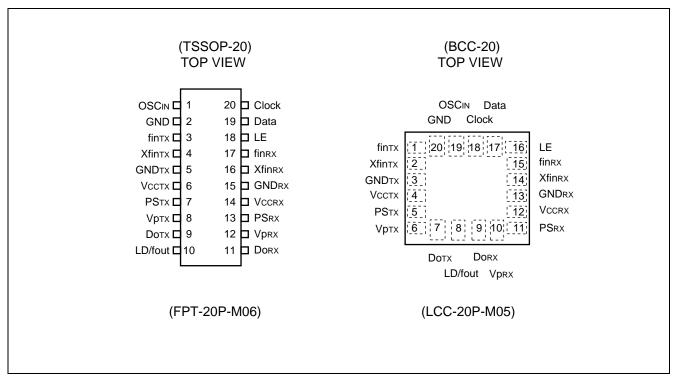
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• Direct power saving function : Power supply current in power saving mode

Typ. 0.1 
$$\mu$$
A (Vcc = Vp = 2.7 V, Ta = +25°C)

- Max. 10  $\mu$ A (Vcc = Vp = 2.7 V) Software selectable charge pump current : 1.5 mA/6.0 mA Typ.
- Dual modulus prescaler: 2600 MHz prescaler (32/33 or 64/65) /1200 MHz prescaler (16/17 or 32/33)
- 23-bit shift register
- Serial input binary 14-bit programmable reference divider : R = 3 to 16,383
- Serial input programmable divider consisting of :
  - Binary 7-bit swallow counter: 0 to 127
  - Binary 11-bit programmable counter: 3 to 2,047
- Built-in high-speed tuning, low-noise phase comparator, current-switching type constant current circuit
- On-chip phase control for phase comparator
- On-chip phase comparator for fast lock and low noise
- · Built-in digital locking detector circuit to detect PLL locking and unlocking
- Operating temperature : Ta = −40 to +85 °C
- Serial data format compatible with MB15F08SL

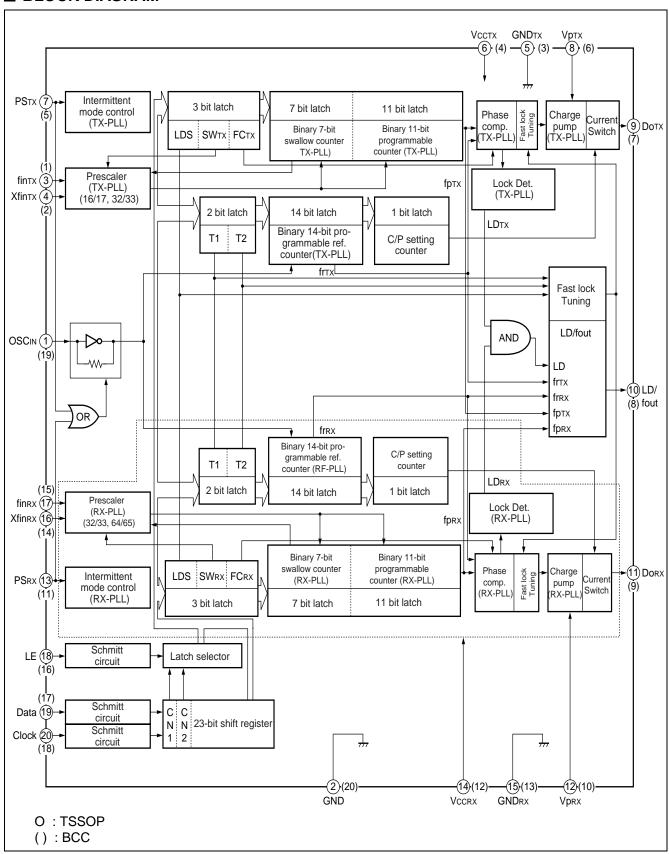
#### **■ PIN ASSIGNMENTS**



# **■ PIN DESCRIPTION**

Pin	no.	Pin name	1/0	Descriptions
TSSOP	ВСС	Pin name	1/0	Descriptions
1	19	OSCIN	I	The programmable reference divider input pin. TCXO should be connected with an AC coupling capacitor.
2	20	GND	_	Ground pin for OSC input buffer and the shift register circuit.
3	1	fin⊤x	I	Prescaler input pin for the TX-PLL. Connection to an external VCO should be via AC coupling.
4	2	Xfin⊤x	I	Prescaler complimentary input pin for the TX-PLL section. This pin should be grounded via a capacitor.
5	3	GND <sub>TX</sub>	_	Ground pin for the TX-PLL section.
6	4	Vсстх	_	Power supply voltage input pin for the TX-PLL section (except for the charge pump circuit), the oscillator input buffer and the shift register.
7	5	РЅтх	ı	Power saving mode control pin for the TX-PLL section. This pin must be set at "L" when the power supply is started up. (Open is prohibited.) $PS_{TX} = \text{"H"}; \text{ Normal mode/PS}_{TX} = \text{"L"}; \text{ Power saving mode}$
8	6	Vртх		Power supply voltage input pin for the TX-PLL charge pump.
9	7	<b>D</b> отх	0	Charge pump output pin for the TX-PLL section.
10	8	LD/fout	0	Lock detect signal output (LD) /phase comparator monitoring output (fout) .The output signal is selected by LDS bit in the serial data. LDS bit = "H"; outputs fout signal/LDS bit = "L"; outputs LD signal
11	9	Dorx	0	Charge pump output pin for the RX-PLL section.
12	10	Vprx		Power supply voltage input pin for the RX-PLL charge pump.
13	11	PS <sub>RX</sub>	I	Power saving mode control pin for the RX-PLL section. This pin must be set at "L" when the power supply is started up. (Open is prohibited.) PSRX = "H"; Normal mode/PSRX = "L"; Power saving mode
14	12	Vccrx	—	Power supply voltage input pin for the RX-PLL section (except for the charge pump circuit)
15	13	GND <sub>RX</sub>		Ground pin for the RX-PLL section
16	14	Xfin <sub>RX</sub>	I	Prescaler complimentary input pin for the RX-PLL section. This pin should be grounded via a capacitor.
17	15	fin <sub>RX</sub>	I	Prescaler input pin for the RX-PLL. Connection to an external VCO should be via AC coupling.
18	16	LE	I	Load enable signal input pin (with the schmitt trigger circuit) When LE is set "H", data in the shift register is transferred to the corresponding latch according to the control bit in a serial data.
19	17	Data	I	Serial data input pin (with the schmitt trigger circuit) Data is transferred to the corresponding latch (TX-ref. counter, TX-prog. counter, RX-ref.counter, RX-prog.counter) according to the control bit in a serial data.
20	18	Clock	I	Clock input pin for the 23-bit shift register (with a schmitt trigger circuit) One bit of data is shifted into the shift register on a rising edge of the clock.

## **■ BLOCK DIAGRAM**



## ■ ABSOLUTE MAXIMUM RATINGS

Parameter		Symbol	Rat	ting	Unit
Faiaii	ietei	Symbol	Min.	Max.	Offic
Power supply volta	go.	Vcc	-0.5	4.0	V
Fower Supply Volta	ge	Vp	Vcc	4.0	V
Input voltage	Input voltage		-0.5	Vcc + 0.5	V
Output voltage	LD/fout	Vo	GND	Vcc	V
Output voltage	Dotx, Dorx	V <sub>DD</sub>	GND	Vp	V
Storage temperature		Tstg	-55	+125	°C

WARNING: Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

#### ■ RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol		Value		Unit	Remarks	
raiailletei	Syllibol	Min.	Тур.	Max.	Offic		
Dower oupply voltogo	Vcc	2.4	2.7	3.6	V	Vccrx = Vcctx	
Power supply voltage	Vp	Vcc	2.7	3.6	V		
Input voltage	Vı	GND	_	Vcc	V		
Operating temperature	Ta	-40	_	+85	°C		

Note: • Vccrx, Vprx, Vcctx and Vptx must supply equal voltage.

Even if either RX-PLL or TX-PLL is not used, power must be supplied to Vccrx, Vprx, Vcctx and Vptx to keep them equal.

It is recommended that the non-use PLL is controlled by power saving function.

- Although this device contains an anti-static element to prevent electrostatic breakdown and the circuitry has been improved in electrostatic protection, observe the following precautions when handling the device.
  - When storing and transporting the device, put it in a conductive case.
  - Before handling the device, confirm the (jigs and) tools to be used have been uncharged (grounded) as well as yourself. Use a conductive sheet on working bench.
  - Before fitting the device into or removing it from the socket, turn the power supply off.
  - When handling (such as transporting) the device mounted board, protect the leads with a conductive sheet.

WARNING: The recommended operating conditions are required in order to ensure the normal operation of the semiconductor device. All of the device's electrical characteristics are warranted when the device is operated within these ranges.

> Always use semiconductor devices within their recommended operating condition ranges. Operation outside these ranges may adversely affect reliability and could result in device failure.

> No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their FUJITSU representatives beforehand.

# **■ ELECTRICAL CHARACTERISTICS**

 $(Vcc = 2.4 \text{ V to } 3.6 \text{ V}, \text{ Ta} = -40 \,^{\circ}\text{C to } +85 \,^{\circ}\text{C})$ 

D		0	O and Philade		Value		11
Parameter		Symbol	Condition	Min.	Тур.	Max.	Unit
Power supply current		<b>І</b> сстх *1	finтx = 910 MHz Vccтx = Vpтx = 2.7 V	1.1	1.7	2.4	mA
Tower supply durient		Iccrx *1	finrx = 2500 MHz Vccrx = Vprx = 2.7 V	1.8	2.8	3.9	mA
Power saving current		IPSTX	PSTX = PSRX = "L"	_	0.1 *2	10	μΑ
ower saving current		Ipsrx	$PS_{TX} = PS_{RX} = L$	_	0.1 *2	10	μΑ
	fin⊤x *³	fin⊤x	TX PLL	100	_	1200	MHz
Operating frequency	fin <sub>RX</sub> *3	fin <sub>RX</sub>	RX PLL	400	_	2600	MHz
	OSCIN	fosc	_	3	_	40	MHz
	fin⊤x	Pfin⊤x	TX PLL, 50 Ω system	-15	_	+2	dBm
Input sensitivity	fin <sub>RX</sub>	Pfin <sub>RX</sub>	RX PLL, 50 Ω system	-15		+2	dBm
	OSCIN	Vosc	_	0.5	_	Vcc	V <sub>P-P</sub>
"H" level input voltage	Data,	ViH	Schmitt trigger input	0.7 Vcc + 0.4	_	_	٧
"L" level input voltage	LE, Clock	VIL	Schmitt trigger input	_	_	0.3 Vcc - 0.4	٧
"H" level input voltage	РЅтх	Vін	_	0.7 Vcc	_	_	V
"L" level input voltage	PS <sub>RX</sub>	VIL	_			0.3 Vcc	V
"H" level input current	Data LE	I <sub>IH</sub> *4	_	-1.0		+1.0	μА
"L" level input current	Clock PS <sub>TX</sub> PS <sub>RX</sub>	I <sub>IL</sub> *4	_	-1.0	_	+1.0	μΑ
"H" level input current	000	Іін	_	0		+100	μΑ
"L" level input current	OSCIN	<b>I</b> ı∟ *4	_	-100	_	0	μΑ
"H" level output voltage	LD/fout	Vон	$V_{CC} = Vp = 2.7 V,$ $I_{OH} = -1 \text{ mA}$	Vcc - 0.4	_	_	V
"L" level output voltage		Vol	Vcc = Vp = 2.7  V, IoL = 1  mA			0.4	V
"H" level output voltage	Dотx	V <sub>DOH</sub>	$V_{CC} = Vp = 2.7 V,$ $I_{DOH} = -0.5 \text{ mA}$	Vp - 0.4	_	_	٧
"L" level output voltage	Dorx	VDOL	$V_{CC} = Vp = 2.7 V$ , $I_{DOL} = 0.5 mA$	_	_	0.4	V
High impedance cutoff current	Dotx Dorx	loff	$V_{CC} = Vp = 2.7 \text{ V}$ $V_{OFF} = 0.5 \text{ V to Vp} - 0.5 \text{ V}$	_	_	2.5	nA
"H" level output current	I D/facet	<b>І</b> он *4	Vcc = Vp = 2.7 V	_		-1.0	mA
"L" level output current	LD/fout	lol	Vcc = Vp = 2.7 V	1.0	_	_	mA

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## (Continued)

 $(Vcc = 2.4 \text{ V to } 3.6 \text{ V}, Ta = -40 ^{\circ}\text{C to } +85 ^{\circ}\text{C})$ 

Parameter	Parameter		Condit	rion		Value			
raiailletei		Symbol	Condit	.1011	Min.	Тур.	Max.	Unit	
"H" level output current	<b>Do</b> тх *8	<b>I</b> дон *4	$V_{CC} = V_p = 2.7 V,$ $V_{DOH} = V_p / 2,$	CS bit = "H"	-8.2	-6.0	-4.1	mA	
	Dorx	IDOH	Ta = +25 °C	CS bit = "L"	-2.2	-1.5	-0.8	mA	
"L" level output current	<b>Do</b> тx *8	IDOL	$V_{CC} = V_{p} = 2.7 V,$ $V_{DOL} = V_{p} / 2,$	CS bit = "H"	4.1	6.0	8.2	mA	
L level output current	Dorx	IDOL	Ta = +25 °C	CS bit = "L"	0.8	1.5	2.2	mA	
	IDOL/IDOH	<b>І</b> ромт *5	V <sub>DO</sub> = Vp / 2		_	3	_	%	
Charge pump	vs V <sub>DO</sub>	loovd *6	$0.5 \text{ V} \leq \text{V}_{\text{DO}} \leq \text{Vp}$	– 0.5 V	_	10	_	%	
current rate	vs Ta	IDOTA *7	$-40 \text{ °C} \le \text{Ta} \le +8$ $V_{DO} = Vp / 2$	5 °C,	_	5	_	%	

<sup>\*1 :</sup> Conditions ; fosc = 12.8 MHz, Ta =  $\pm$ 25 °C, SW = "L" in locking state.

\*2 :  $V_{CCTX} = V_{DTX} = V_{CCRX} = V_{DRX} = 2.7 \text{ V}$ , fosc = 12.8 MHz, Ta = +25 °C, in power saving mode. PS<sub>TX</sub> = PS<sub>RX</sub> = GND V<sub>IH</sub> = V<sub>CC</sub>, V<sub>IL</sub> = GND (at CLK, Data, LE)

\*3 : AC coupling. 1000 pF capacitor is connected under the condition of Min. operating frequency.

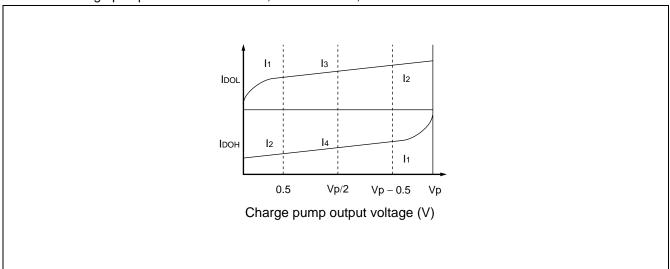
\*4: The symbol "-" (minus) means the direction of current flow.

\*5 : Vcc = Vp = 2.7 V,  $Ta = +25 \, ^{\circ}\text{C} (||I_3| - |I_4||) / [ (|I_3| + |I_4|) / 2] \times 100 (%)$ 

\*6 : Vcc = Vp = 2.7 V,  $Ta = +25 \, ^{\circ}\text{C} \, \left[ \, \left( \left| \left| I_2 \right| - \left| I_1 \right| \right| \right) \, / \, 2 \right] / \, \left[ \, \left( \left| I_1 \right| + \left| I_2 \right| \right) \, / \, 2 \right] \times 100 \, \left( \% \right) \, \right]$  (Applied to both IDOL and IDOH)

\*7 : Vcc = Vp = 2.7 V, [||Ibo(+85 °c)| - |Ibo(-40 °c)|| / 2] / [|Ibo(+85 °c)| + |Ibo(-40 °c)| / 2] × 100 (%) (Applied to both IboL and IboH)

\*8 : When Charge pump current is measured, set LDS = "L", T1 = "L" and T2 = "H".



#### **■ FUNCTIONAL DESCRIPTION**

#### 1. Pulse swallow function

 $fvco = [(P \times N) + A] \times fosc \div R$ 

fvco: Output frequency of external voltage controlled oscillator (VCO)

P : Preset divide ratio of dual modulus prescaler (16 or 32 for TX-PLL, 32 or 64 for RX-PLL)

N : Preset divide ratio of binary 11-bit programmable counter (3 to 2,047) A : Preset divide ratio of binary 7-bit swallow counter ( $0 \le A \le 127$ , A < N)

fosc: Reference oscillation frequency (OSC<sub>IN</sub> input frequency)

R : Preset divide ratio of binary 14-bit programmable reference counter (3 to 16,383)

#### 2. Serial Data Input

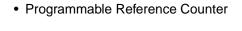
The serial data is entered using three pins, Data pin, Clock pin, and LE pin. Programmable dividers of TX/RX-PLL sections, programmable reference dividers of TX/RX-PLL sections are controlled individually.

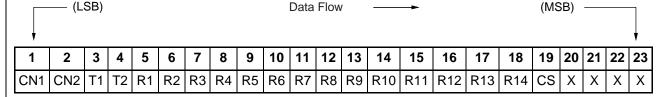
The serial data of binary data is entered through Data pin.

On rising edge of Clock, one bit of the serial data is transferred into the shift register. On a rising edge of load enable signal, the data stored in the shift register is transferred to one of latches depending upon the control bit data setting.

	The programmable reference counter for the TX-PLL	The programmable reference counter for the RX-PL	The programmable counter and the swallow counter for the TX-PLL	The programmable counter and the swallow counter for the RX-PLL	
CN1	0	1	0	1	
CN2	0	0	1	1	

#### (1) Shift Register Configuration





CS : Charge pump current select bit

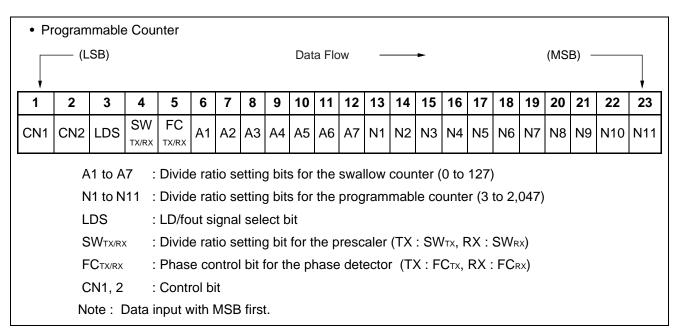
R1 to R14: Divide ratio setting bits for the programmable reference counter (3 to 16,383)

T1, 2 : LD/fout output setting bit

CN1, 2 : Control bit

X : Dummy bits (Set "0" or "1")

Note: Data input with MSB first.



#### (2) Data setting

• Binary 14-bit Programmable Reference Counter Data Setting

Divide ratio	R14	R13	R12	R11	R10	R9	R8	R7	R6	R5	R4	R3	R2	R1
3	0	0	0	0	0	0	0	0	0	0	0	0	1	1
4	0	0	0	0	0	0	0	0	0	0	0	1	0	0
•	•	•	•	•	•	•	•	•	•	•	•	•	•	•
•	•	•	•					•			•	•	•	•
16383	1	1	1	1	1	1	1	1	1	1	1	1	1	1

Note: Divide ratio less than 3 is prohibited.

Binary 11-bit Programmable Counter Data Setting

Divide ratio	N11	N10	N9	N8	N7	N6	N5	N4	N3	N2	N1
3	0	0	0	0	0	0	0	0	0	1	1
4	0	0	0	0	0	0	0	0	1	0	0
•	•	•	•	•	•	•	•	•	•	•	•
			•	•		•	•		•	•	
2047	1	1	1	1	1	1	1	1	1	1	1

Note: Divide ratio less than 3 is prohibited.

• Binary 7-bit Swallow Counter Data Setting

Divide ratio	A7	<b>A6</b>	A5	<b>A4</b>	А3	<b>A2</b>	<b>A</b> 1
0	0	0	0	0	0	0	0
1	0	0	0	0	0	0	1
•	•	•	•	•	•	•	•
•	•	•	•	•	•	•	•
•	•	•	•	•	•	•	•
127	1	1	1	1	1	1	1

## • Prescaler Data Setting

Divide ratio	SW = "H"	SW = "L"
Prescaler divide ratio TX-PLL	16/17	32/33
Prescaler divide ratio RX-PLL	32/33	64/65

## • Charge Pump Current Setting

Current value	CS
±6.0 mA	1
±1.5 mA	0

## • LD/fout output Selectable Bit Setting

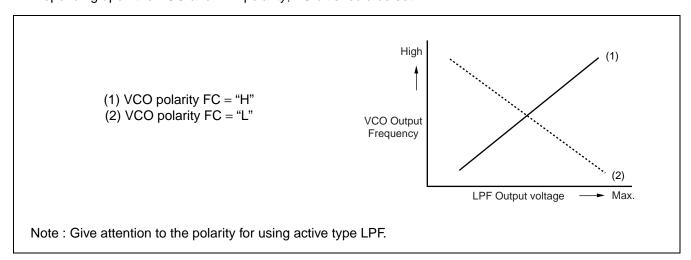
LD/fout	pin state	LDS	T1	T2
		0	0	0
LD o	utput	0	1	0
		0	1	1
	fr⊤x	1	0	0
fout	fr <sub>RX</sub>	1	1	0
output	fртx	1	0	1
	fp <sub>RX</sub>	1	1	1

## • Phase Comparator Phase Switching Data Setting

Phase comparator input	FC = "H"	FC = "L"
	Dotx/Dorx	Dotx/Dorx
fr > fp	Н	L
fr < fp	L	Н
fr = fp	Z	Z

Z: High-impedance

Depending upon the VCO and LPF polarity, FC bit should be set.



# 3. Power Saving Mode (Intermittent Mode Control Circut)

Status	PSTx/PSRx pins
Normal mode	Н
Power saving mode	L

The intermittent mode control circuit reduces the PLL power consumption.

By setting the PS pins low, the device enters into the power saving mode, reducing the current consumption. See the Electrical Characteristics chart for the specific value.

The phase detector output, Do, becomes high impedance.

For the dual PLL, the lock detector, LD, is as shown in the LD Output Logic table.

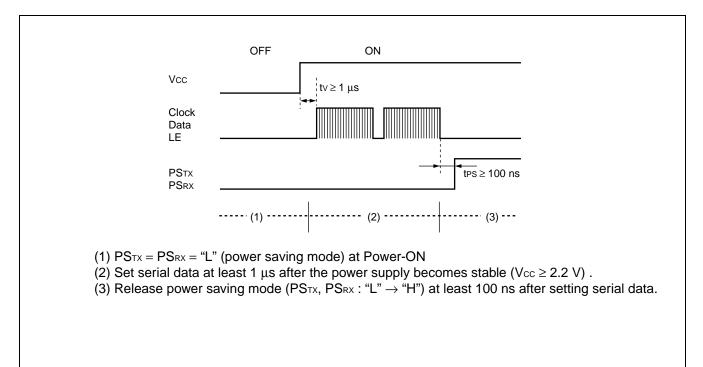
Setting the PS pins high, releases the power saving mode, and the device works normally.

The intermittent mode control circuit also ensures a smooth startup when the device returns to normal operation. When the PLL is returned to normal operation, the phase comparator output signal is unpredictable. This is because of the unknown relationship between the comparison frequency (fp) and the reference frequency (fr) which can cause a major change in the comparator output, resulting in a VCO frequency jump and an increase in lockup time.

To prevent a major VCO frequency jump, the intermittent mode control circuit limits the magnitude of the error signal from the phase detector when it returns to normal operation.

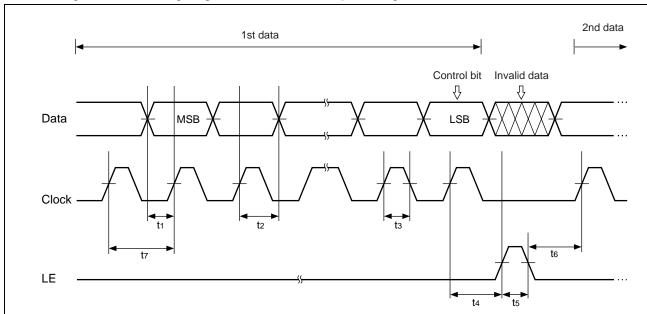
Notes: • When power (Vcc) is first applied, the device must be in standby mode, PSτx = PSκx = Low, for at least 1 μs.

• PS pins must be set at "L" at Power-ON



# 4. Serial data input timing

Divide ratio setting is performed through a serial interface using the Data pin, Clock pin, and LE pin. Setting data is read into the shift register at the rise of the Clock signal, and transferred to a latch at the rise of the LE signal. The following diagram shows the data input timing.

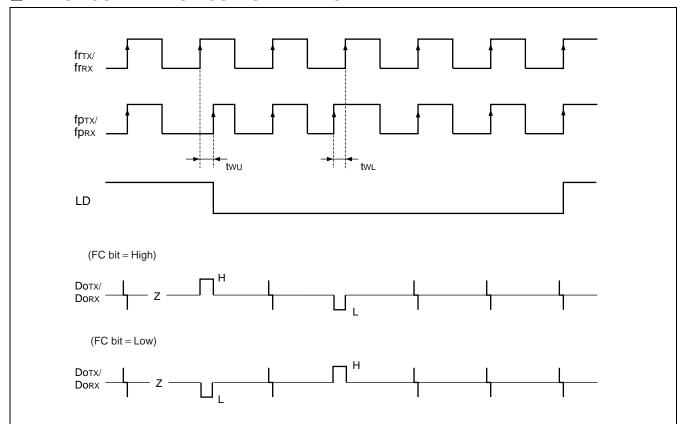


Parameter	Min.	Тур.	Max.	Unit
t <sub>1</sub>	20	_	_	ns
<b>t</b> 2	20	_	_	ns
<b>t</b> 3	30	_	_	ns
t <sub>4</sub>	30	_	_	ns

Parameter	Min.	Тур.	Max.	Unit
<b>t</b> 5	100	_	_	ns
<b>t</b> 6	20	_	_	ns
t <sub>7</sub>	100			ns

Note: LE should be "L" when the data is transferred into the shift register.

## **■ PHASE COMPARATOR OUTPUT WAVEFORM**



## LD Output Logic Table

TX-PLL section	RX-PLL section	LD output
Locking state/Power saving state	Locking state/Power saving state	Н
Locking state/Power saving state	Unlocking state	L
Unlocking state	Locking state/Power saving state	L
Unlocking state	Unlocking state	L

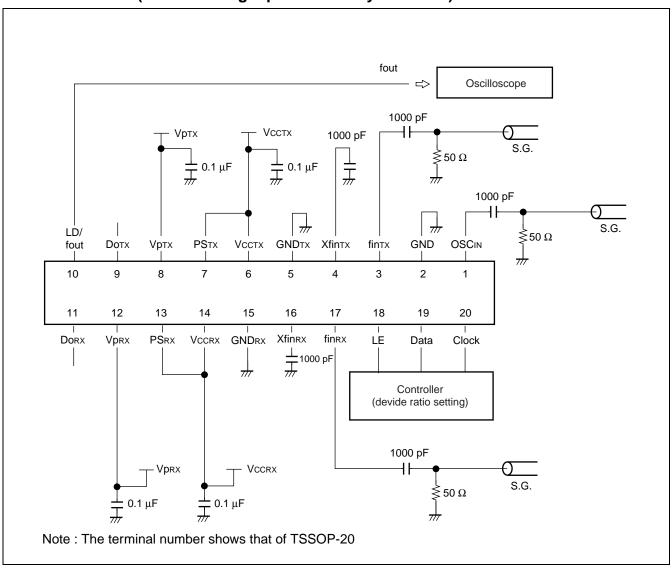
Notes : • Phase error detection range =  $-2 \pi$  to  $+2 \pi$ 

- Pulses on Dotx/Dorx signals are output to prevent dead zone.
- LD output becomes low when phase error is two or more.
- LD output becomes high when phase error is twL or less and continues to be so for three cycles or more.
- $\bullet$   $t_{\text{WU}}$  and  $t_{\text{WL}}$  depend on OSC\_{IN} input frequency as follows.

twu  $\geq$  2/fosc : e.g. twu  $\geq$  156.3 ns when fosc = 12.8 MHz

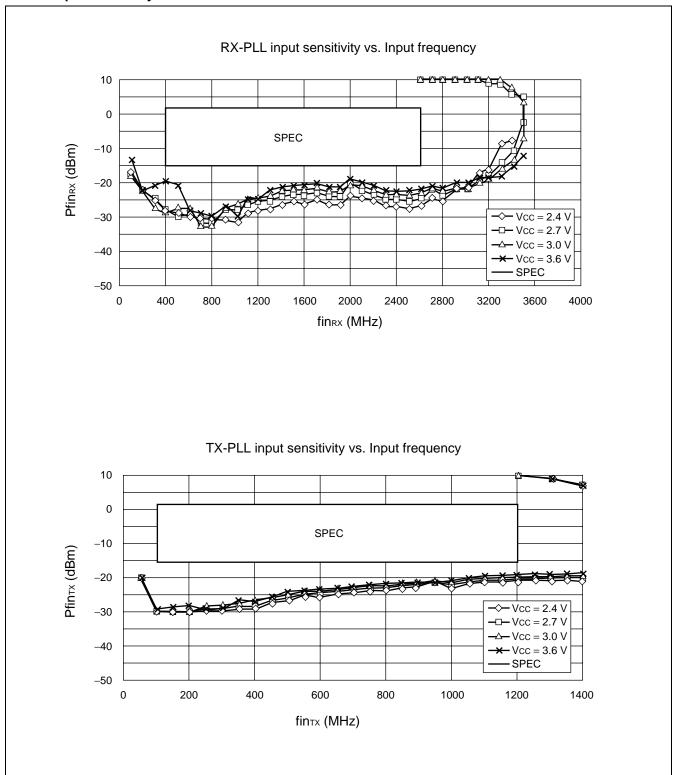
 $t_{WU} \le 4/f_{osc}$ : e.g.  $t_{WL} \le 312.5$  ns when  $f_{osc} = 12.8$  MHz

# ■ TEST CIRCUIT (for Measuring Input Sensitivity fin/OSC<sub>IN</sub>)

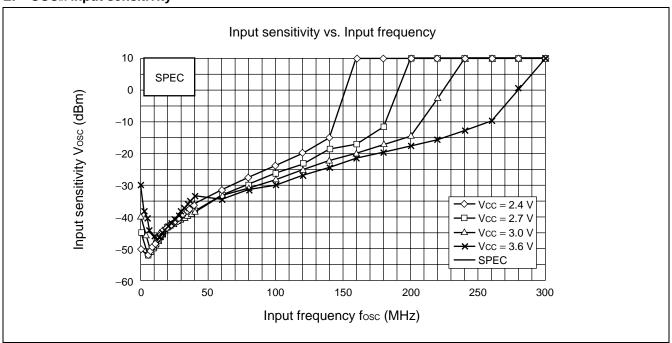


## **■ TYPICAL CHARACTERISTICS**

## 1. fin input sensitivity



# 2. OSC<sub>IN</sub> input sensitivity

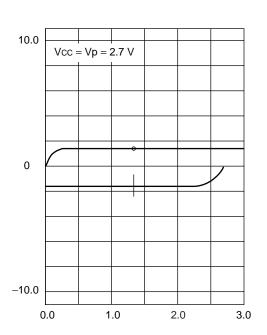


# 3. Do output current (RX PLL)

• 1.5 mA mode

 $I_{\text{DO}} - V_{\text{DO}}$ 

Charge pump output current Ioo (mA)

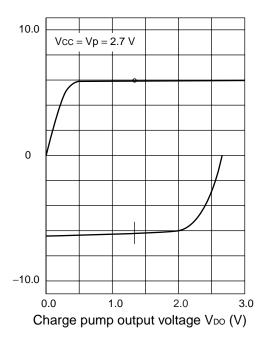


Charge pump output voltage V<sub>DO</sub> (V)

• 6.0 mA mode

 $I_{DO}-V_{DO} \\$ 



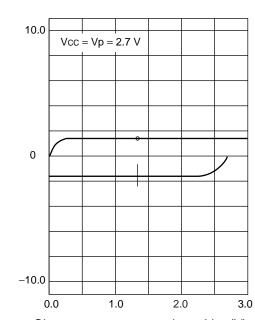


# 4. Do output current (TX PLL)

• 1.5 mA mode

 $I_{\text{DO}} - V_{\text{DO}}$ 

Charge pump output current l∞ (mA)

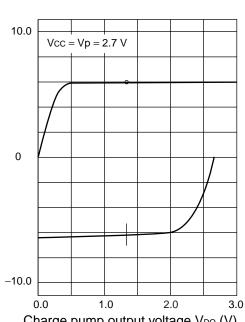


Charge pump output voltage V<sub>DO</sub> (V)

• 6.0 mA mode

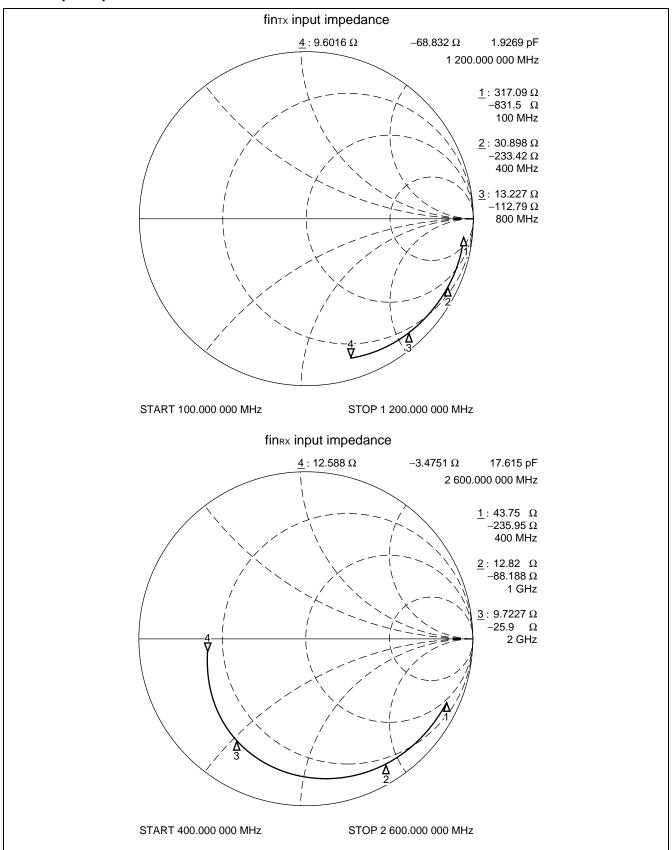
 $I_{\text{DO}} - V_{\text{DO}}$ 

Charge pump output current Ipo (mA)

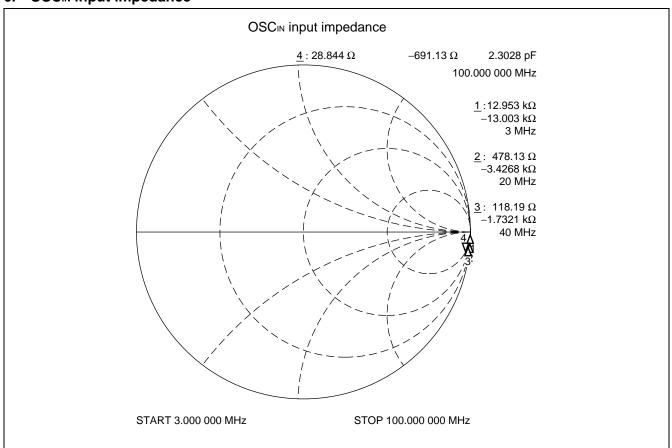


Charge pump output voltage V<sub>DO</sub> (V)

# 5. fin input impedance

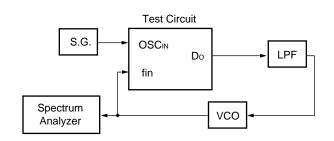


# 6. OSC<sub>IN</sub> input impedance

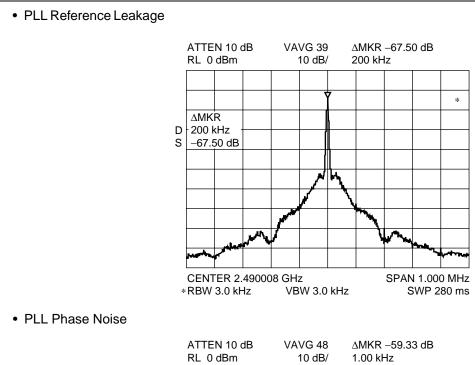


## **■ REFERENCE INFORMATION**

(for Look-up time, Phase noise and Reference leakage)



± 820 pF



\*RBW 100 Hz

RL 0 dBm 10 dB/ 1.00 kHz

D AMKR 1.00 kHz 59.33 dB

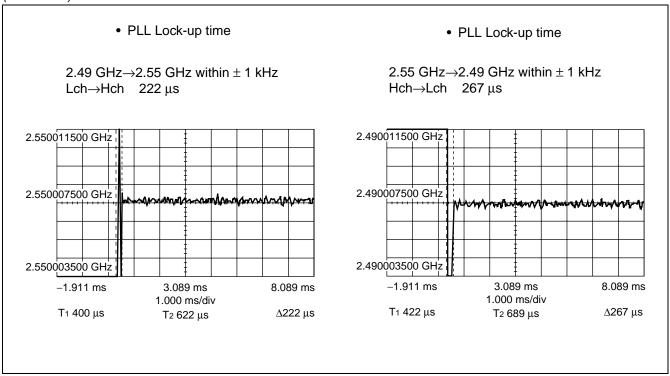
CENTER 2.49000640 GHz SPAN 10.00 kHz

VBW 100 Hz

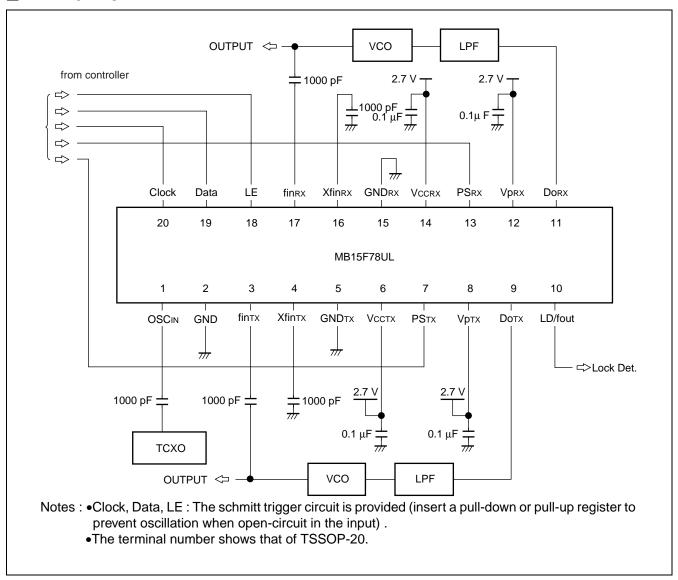
SWP 802 ms

(Continued)

# (Continued)



## **■ APPLICATION EXAMPLE**



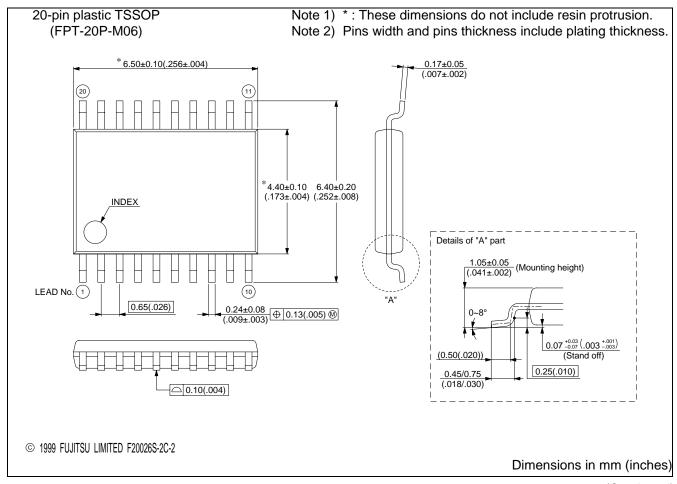
## **■ USAGE PRECAUTIONS**

- (1) Vccrx, Vprx, Vccrx and Vprx must be equal voltage. Even if either RX-PLL or TX-PLL is not used, power must be supplied to Vccrx, Vprx, Vccrx and Vprx to keep them equal. It is recommended that the non-use PLL is controlled by power saving function.
- (2) To protect against damage by electrostatic discharge, note the following handling precautions:
  - -Store and transport devices in conductive containers.
  - -Use properly grounded workstations, tools, and equipment.
  - -Turn off power before inserting or removing this device into or from a socket.
  - -Protect leads with conductive sheet, when transporting a board mounted device.

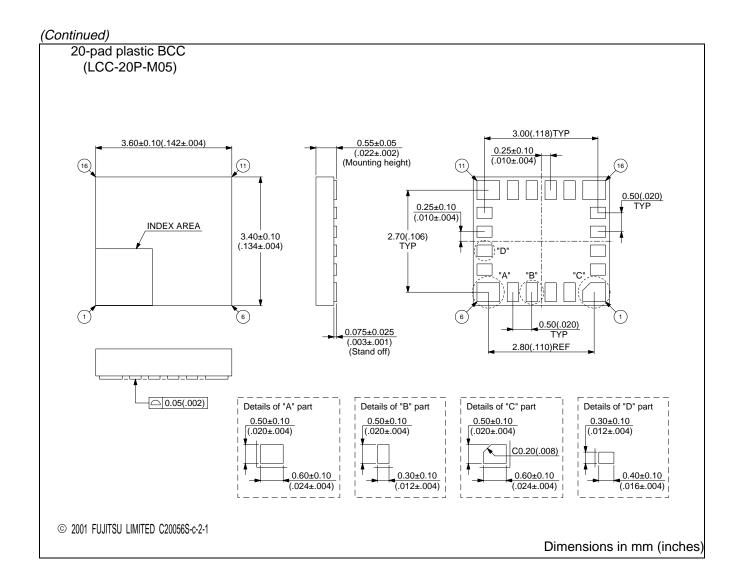
## **■ ORDERING INFORMATION**

Part number	Package	Remarks
MB15F78ULPFT	20-pin, plastic TSSOP (FPT-20P-M06)	
MB15F78ULPVA	20-pad, plastic BCC (LCC-20P-M05)	

## **■ PACKAGE DIMENSIONS**



(Continued)



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